## NSS1C201MZ4, NSV1C201MZ4

# 100 V, 2.0 A, Low V<sub>CE(sat)</sub>

ON Semiconductor's  $e^2$ PowerEdge family of low  $V_{CE(sat)}$  transistors are miniature surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### **Features**

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

## **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	100	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	140	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	7.0	Vdc
Collector Current - Continuous	I <sub>C</sub>	2.0	Α
Collector Current - Peak	I <sub>CM</sub>	3.0	Α

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 1)	800 6.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	155	°C/W
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 2)	2.0 15.6	W mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	64	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P <sub>Dsingle</sub> (Note 3)	710	mW
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

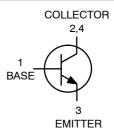
- 1. FR-4 @ 7.6 mm<sup>2</sup>, 1 oz. copper traces.
- 2. FR-4 @ 645 mm<sup>2</sup>, 1 oz. copper traces.
- 3. Thermal response.



## ON Semiconductor®

http://onsemi.com

## 100 VOLTS, 2.0 AMPS NPN LOW V<sub>CE(sat)</sub> TRANSISTOR



## MARKING DIAGRAM



SOT-223 CASE 318E STYLE 1



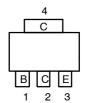
A = Assembly Location

′ = Year

W = Work Week

1C201 = Specific Device Code ■ Pb-Free Package

## **PIN ASSIGNMENT**



Top View Pinout

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS1C201MZ4T1G NSV1C201MZ4T1G	SOT-223 (Pb-Free)	1000/ Tape & Reel
NSS1C201MZ4T3G	SOT-223 (Pb-Free)	4000/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## NSS1C201MZ4, NSV1C201MZ4

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I <sub>C</sub> = 10 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	100			Vdc
Collector – Base Breakdown Voltage (I <sub>C</sub> = 0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	140			Vdc
Emitter – Base Breakdown Voltage (I <sub>E</sub> = 0.1 mAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	7.0			Vdc
Collector Cutoff Current (V <sub>CB</sub> = 140 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>			100	nA
Emitter Cutoff Current (V <sub>EB</sub> = 6.0 Vdc)	I <sub>EBO</sub>			50	nA
ON CHARACTERISTICS					
DC Current Gain (Note 4) $ (I_C = 10 \text{ mA}, V_{CE} = 2.0 \text{ V}) $ $ (I_C = 500 \text{ mA}, V_{CE} = 2.0 \text{ V}) $ $ (I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V}) $ $ (I_C = 2.0 \text{ A}, V_{CE} = 2.0 \text{ V}) $	h <sub>FE</sub>	150 120 80 40		360	
Collector – Emitter Saturation Voltage (Note 4) $ (I_C = 0.1 \text{ A}, I_B = 0.010 \text{ A}) $ $ (I_C = 0.5 \text{ A}, I_B = 0.050 \text{ A}) $ $ (I_C = 1.0 \text{ A}, I_B = 0.100 \text{ A}) $ $ (I_C = 2.0 \text{ A}, I_B = 0.200 \text{ A}) $	V <sub>CE(sat)</sub>			0.030 0.060 0.100 0.180	V
Base – Emitter Saturation Voltage (Note 4) (I <sub>C</sub> = 1.0 A, I <sub>B</sub> = 0.100 A)	V <sub>BE(sat)</sub>			1.10	V
Base – Emitter Turn–on Voltage (Note 4) (I <sub>C</sub> = 1.0 A, V <sub>CE</sub> = 2.0 V)	V <sub>BE(on)</sub>			0.850	V
Cutoff Frequency ( $I_C$ = 100 mA, $V_{CE}$ = 5.0 V, f = 100 MHz)	f <sub>T</sub>		100		MHz
Input Capacitance (V <sub>EB</sub> = 0.5 V, f = 1.0 MHz)	Cibo		305		pF
Output Capacitance (V <sub>CB</sub> = 3.0 V, f = 1.0 MHz)	Cobo		22		pF

<sup>4.</sup> Pulsed Condition: Pulse Width = 300 msec, Duty Cycle  $\leq$  2%.

## **TYPICAL CHARACTERISTICS**

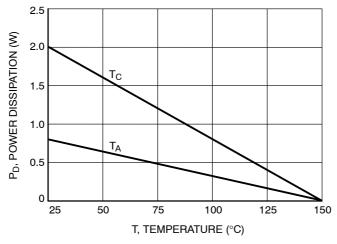
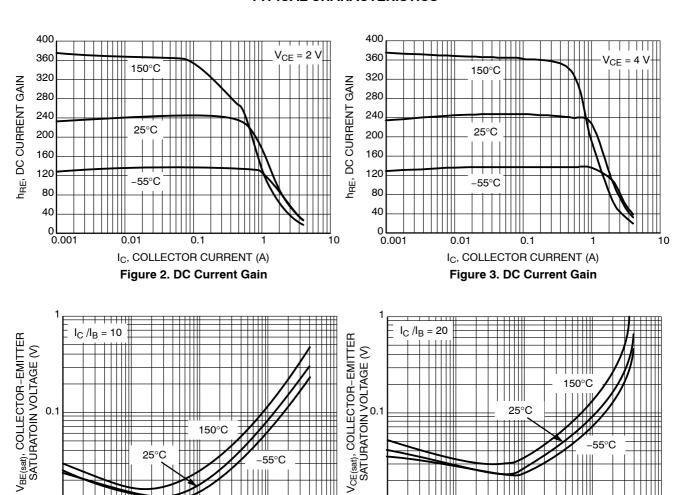


Figure 1. Power Derating

## NSS1C201MZ4, NSV1C201MZ4

### **TYPICAL CHARACTERISTICS**



I<sub>C</sub>, COLLECTOR CURRENT (A)

Figure 4. Collector–Emitter Saturation Voltage

0.1

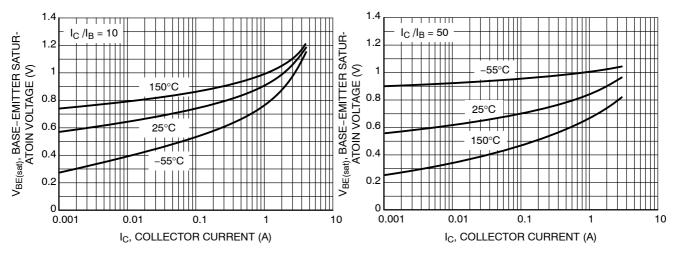
0.001

I<sub>C</sub>, COLLECTOR CURRENT (A)

Figure 5. Collector–Emitter Saturation Voltage

0.1

10



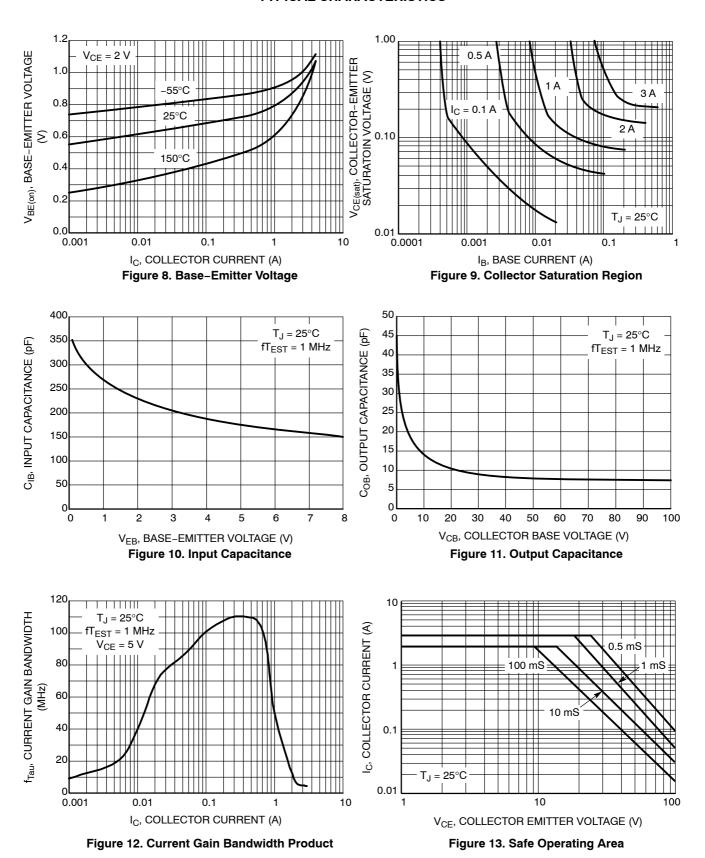
0.001

Figure 6. Base-Emitter Saturation Voltage

Figure 7. Base-Emitter Saturation Voltage

## NSS1C201MZ4, NSV1C201MZ4

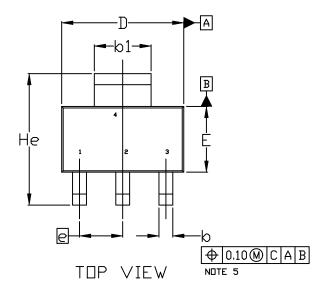
### **TYPICAL CHARACTERISTICS**

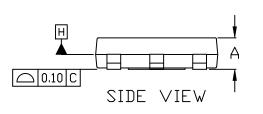


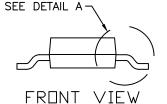


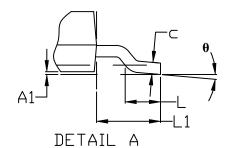
**SOT-223 (TO-261)** CASE 318E-04 ISSUE R

**DATE 02 OCT 2018** 





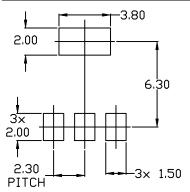




#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS, MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- 5. ALLIS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
- 6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS 6 AND 61.

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	1.50	1.63	1.75	
A1	0.02	0.06	0.10	
b	0.60	0.75	0.89	
b1	2.90	3.06	3.20	
c	0.24	0.29	0.35	
D	6.30	6.50	6.70	
E	3.30	3.50	3.70	
е	2.30 BSC			
L	0.20			
L1	1.50	1.75	2.00	
He	6.70	7.00	7.30	
θ	0°		10°	



RECOMMENDED MOUNTING FOOTPRINT

DOCUMENT NUMBER:	98ASB42680B	Electronic versions are uncontrolled except when accessed directly from the Document Reposite Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOT-223 (TO-261)		PAGE 1 OF 2	

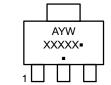
ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

## **SOT-223 (TO-261)** CASE 318E-04 ISSUE R

**DATE 02 OCT 2018** 

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	STYLE 8: CANCELLED	STYLE 9: PIN 1. INPUT 2. GROUND 3. LOGIC 4. GROUND	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	STYLE 12: PIN 1. INPUT 2. OUTPUT 3. NC 4. OUTPUT	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

## GENERIC MARKING DIAGRAM\*



A = Assembly Location

Y = Year W = Work Week

 $XXXXX \ = Specific \ Device \ Code$ 

= Pb-Free Package

(Note: Microdot may be in either location)
\*This information is generic. Please refer to
device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "•", may
or may not be present. Some products may
not follow the Generic Marking.

DOCUMENT NUMBER:	98ASB42680B	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOT-223 (TO-261)		PAGE 2 OF 2

ON Semiconductor and III are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

ON Semiconductor and the are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative